

SDI300N12

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NPT IGBT Modules

Characteristics

T_c = 25°C, unless otherwise specified

Symbol	Conditions	min.	typ.	max.	Units
IGBT					
V _{GE(th)}	V _{GE} = V _{CE} , I _c = 6mA	4.5	5.5	6.5	V
I _{CES}	V _{GE} = 0; V _{CE} = V _{CE(s)} ; T _j = 25(125)°C		0.1	0.3	mA
V _{CE(TO)}	T _j = 25(125)°C		1.4(1.6)	1.6(1.8)	V
r _{CE}	V _{GE} = 15V, T _j = 25(125)°C		5.5(7.5)	7(9.5)	mΩ
V _{CE(sat)}	I _c = 150A; V _{GE} = 15V; chip level		2.5(3.1)	3(3.7)	V
C _{ies}	under following conditions		18	24	
C _{oes}	V _{GE} = 0, V _{CE} = 25V, f = 1MHz		2.5	3.2	nF
C _{res}			1	1.3	
L _{CE}				20	nH
R _{CC'+EE'}	res., terminal-chip T _c = 25(125)°C		0.35(0.5)		mΩ
t _{d(on)}	under following conditions: V _{CC} = 600V, I _c = 150A		250	400	ns
t _r	R _{Gon} = R _{Goff} = 4.7Ω, T _j = 125°C		90	160	ns
t _{d(off)}	V _{GE} = ± 15V		550	700	ns
t _f			70	100	ns
E _{on} (E _{off})			28(26)		mJ
Inverse Diode under following conditions:					
V _F = V _{EC}	I _F = 200A; V _{GE} = 0V; T _j = 25(125)°C		2(1.8)	2.5	V
V _(TO)	T _j = 125°C		1.1	1.2	V
r _T	T _j = 125°C		3	5.5	mΩ
I _{RRM}	I _F = 200A; T _j = 25(125)°C		70(105)		A
Q _{rr}	di/dt = A/us		10(26)		uC
E _{rr}	V _{GE} = V				mJ
FWD under following conditions:					
V _F = V _{EC}	I _F = 100A; V _{GE} = 0V; T _j = 25(125)°C		1.9(1.7)	2.4	V
V _(TO)	T _j = 125°C			1.2	V
r _T	T _j = 125°C		3	3.5	mΩ
I _{RRM}	I _F = 200A; T _j = 25(125)°C		80(140)		A
Q _{rr}	di/dt = A/us		10(34)		uC
E _{rr}	V _{GE} = V				mJ
Thermal Characteristics					
R _{th(j-c)}	per IGBT			0.075	K/W
R _{th(j-c)D}	per Inverse Diode			0.18	K/W
R _{th(j-c)FD}	per FWD			0.15	K/W
R _{th(c-s)}	per module			0.038	K/W
Mechanical Data					
M _s	to heatsink M6	3		5	Nm
M _t	to terminals M6	2.5		5	Nm
w				325	g

